Features

150 Watts peak pulse power (tp = 8/20μs)
Tiny SOT143 package
Bidirectional configurations
Solid-state silicon-avalanche technology
Low clamping voltage
Low leakage current
Low capacitance (Cj=30pF typ I/O to I/O.)
Protection one data/power line to:
IEC 61000-4-2 ±8kV contact ±15kV air
IEC 61000-4-4 (EFT) 40A (5/50ns)
IEC 61000-4-5 (Lightning) 10A (8/20μs)

Applications

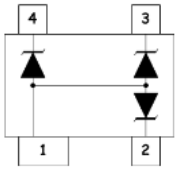
USB2.0,
Ethernet
Notebooks, Desktops, and Servers
Video Line Protection

Mechanical Data

SOT143 package
Molding compound flammability rating: UL 94V-0
Packaging: Tape and Reel
RoHS/WEEE Compliant

503B

SOT143



Schematic & PIN Configuration

Absolute Maximum Rating

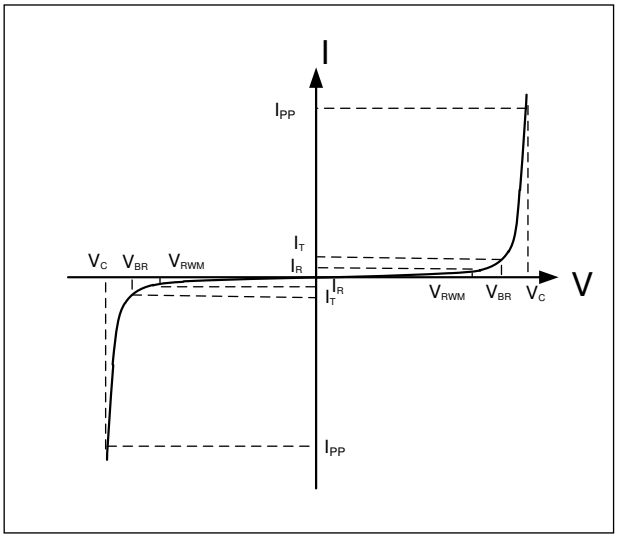
Rating	Symbol	Value	Units
Peak Pulse Power (t_p =8/20μs)	P_{PP}	150	Watts
Peak Pulse Current (t_p =8/20μs) (note1)	I_{pp}	10	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	15 8	kV
Lead Soldering Temperature	T_L	260(10seconds)	℃
Junction Temperature	T_J	-55 to + 125	℃
Storage Temperature	T_{stg}	-55 to + 125	℃

Electrical Characteristics (TA = 25°C unless otherwise noted)

Part Number	Device Marking	V_{RWM} (V)	V_{BR} (V)	I_T (mA)	V_C @1A	Vc		I_R μA (Max)	C (Pf) (Typ.)
						(Max)	(@A)		
SP0503BAHTG	503B	5	6	1	10	15	10	1	30

Electronics Parameter (TA = 25°C unless otherwise noted)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current



Note:. 8/20μs pulse waveform.

RATING AND CHARACTERISTIC CURVES

Figure 1: Peak Pulse Power vs. Pulse Time

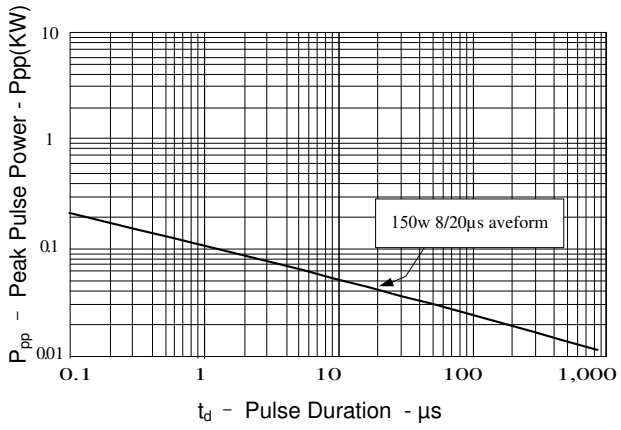


Figure 2: Power Derating Curve

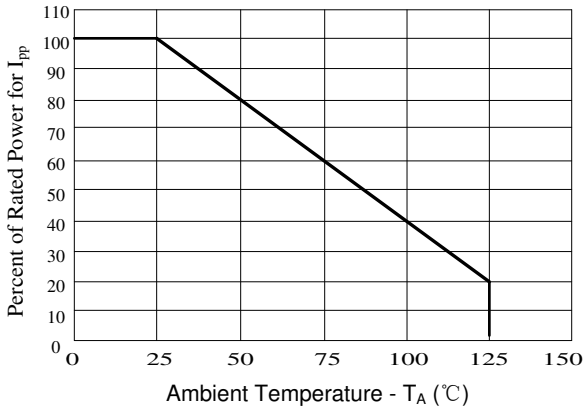


Figure3: Pulse Waveform

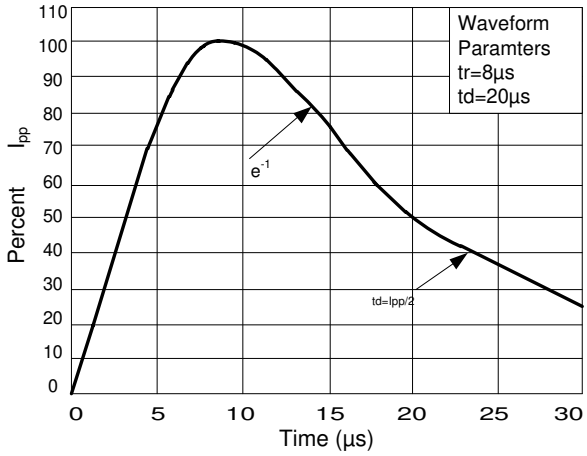
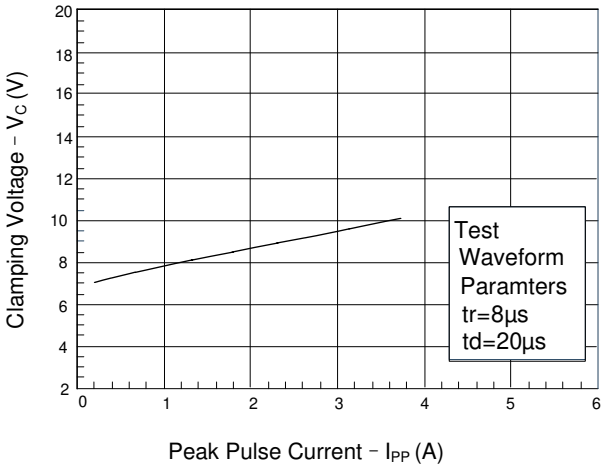


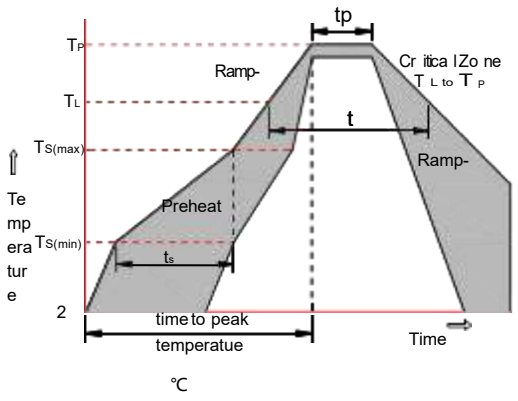
Figure 4: Clamping Voltage vs.Ipp



Soldering parameters

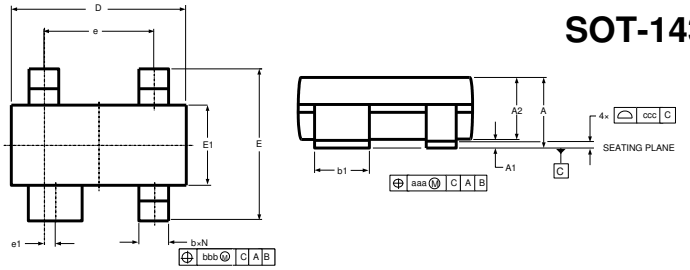
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition



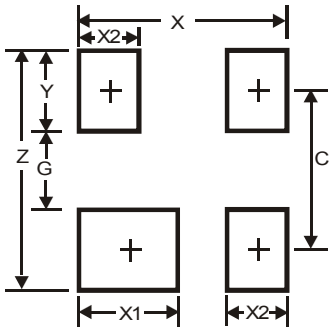
Package Dimensions & Suggested Pad Layout

SOT-143



DIMENSIONS				
SYMBOL	MILLIMETER		INCHES	
	MIN	MAX	MIN	MAX
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
b1	0.750	0.900	0.030	0.035
D	2.800	3.000	0.110	0.118
e	1.800	2.000	0.071	0.079
e1	0.200TYP		0.008TYP	
E	2.250	2.550	0.089	0.100
E1	1.200	1.400	0.047	0.055
θ	0°	8°	0°	8°
aaa	.006		0.15	
bbb	.008		0.20	
ccc	.004		0.10	

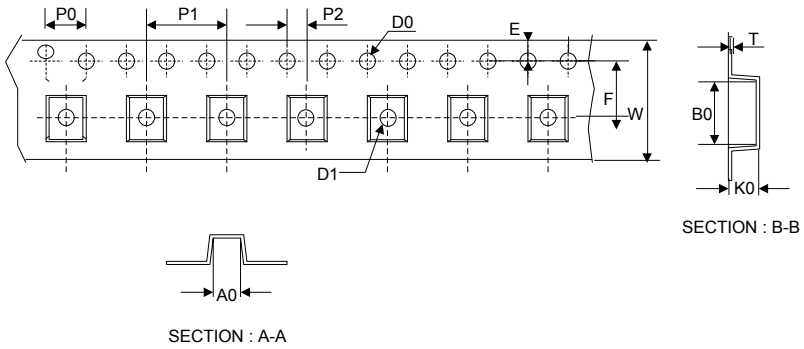
Dimensions in inches and (millimeters)



Dimensions	Value (in mm)
Z	2.90
G	1.20
X	2.50
X1	1.00
X2	0.60
Y	0.85
C	2.05

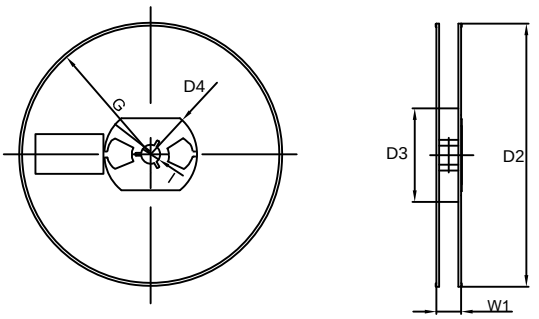
Tape & rell specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.20
P1	4.00±0.20
P2	2.00±0.20
D0	1.55±0.20
D1	1.20±0.20
E	1.55±0.25
F	3.60±0.20
W	8.00±0.20
A0	3.80±0.20
B0	3.10±0.20
K0	1.40±0.20
T	0.20±0.20

7” Reel



D2	177.0±5.0
D3	55Min.
D4	R24.6±2.0
G	R82.0±2.0
I	13.0±2.0
W1	10.20±3.0

Quantity: 3000PCS